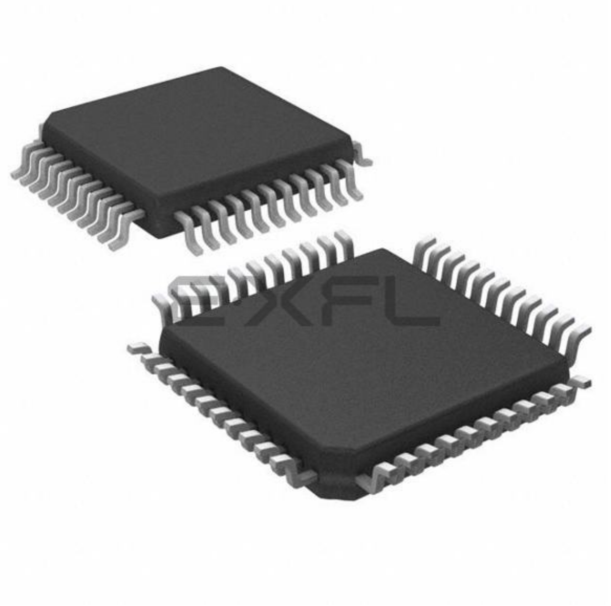


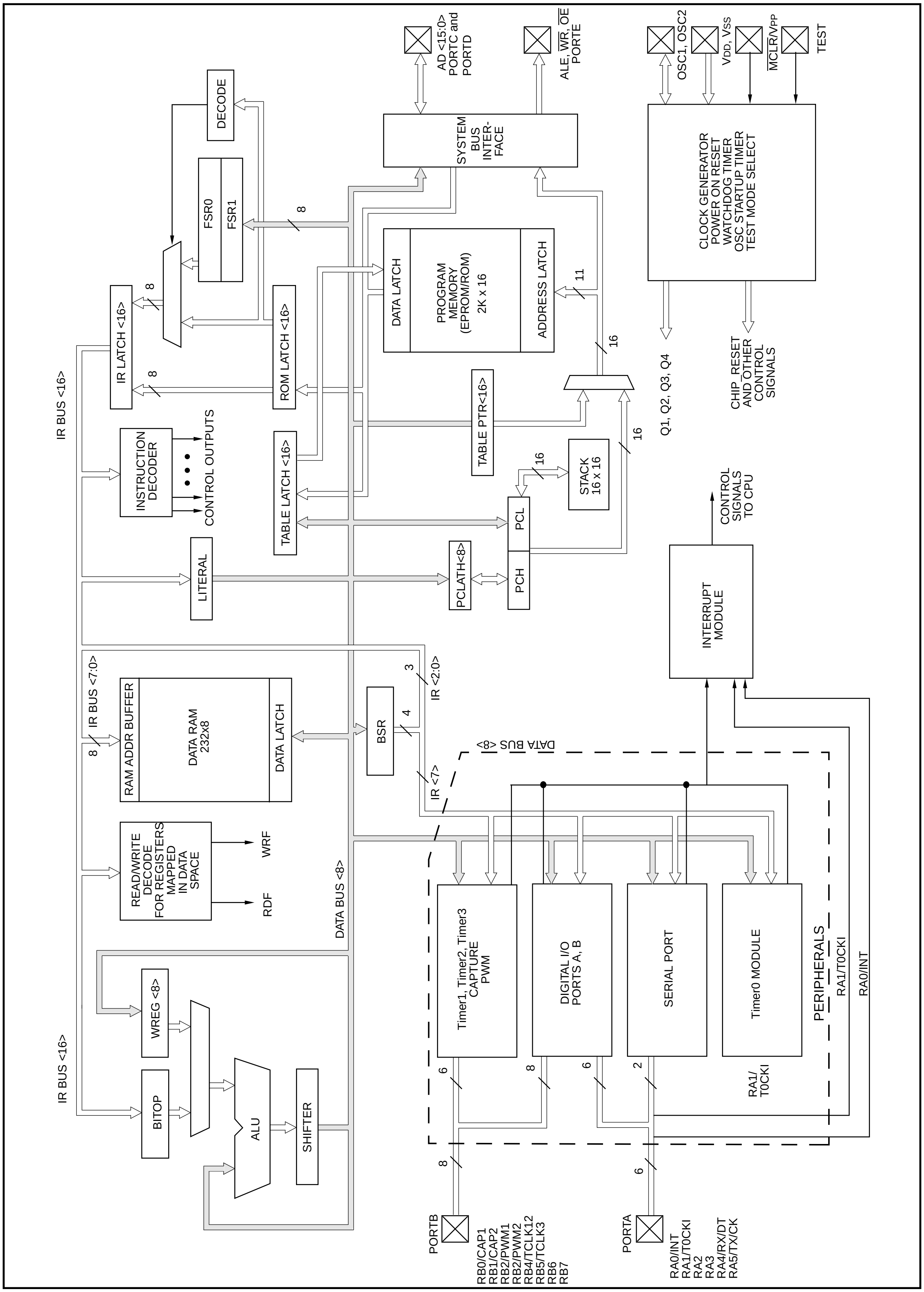
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	33MHz
Connectivity	UART/USART
Peripherals	POR, PWM, WDT
Number of I/O	33
Program Memory Size	8KB (4K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	454 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 6V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-QFP
Supplier Device Package	44-MQFP (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c43-33i-pq

FIGURE 3-1: PIC17C42 BLOCK DIAGRAM



3.1 Clocking Scheme/Instruction Cycle

The clock input (from OSC1) is internally divided by four to generate four non-overlapping quadrature clocks, namely Q1, Q2, Q3, and Q4. Internally, the program counter (PC) is incremented every Q1, and the instruction is fetched from the program memory and latched into the instruction register in Q4. The instruction is decoded and executed during the following Q1 through Q4. The clocks and instruction execution flow are shown in Figure 3-3.

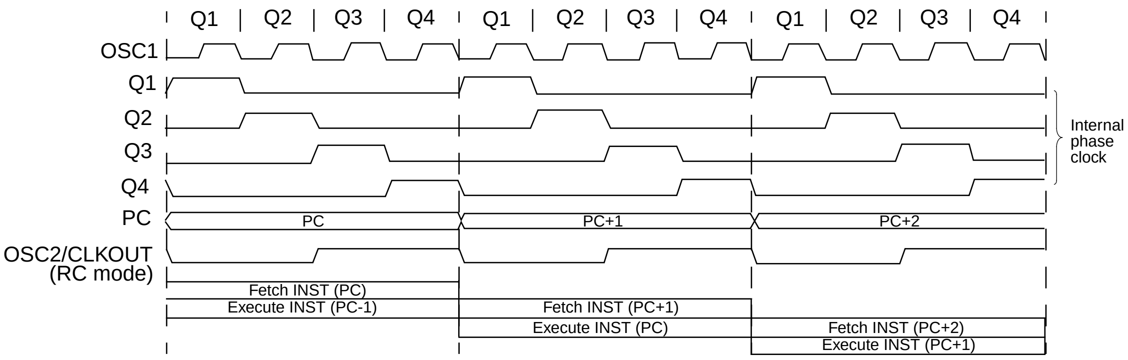
3.2 Instruction Flow/Pipelining

An “Instruction Cycle” consists of four Q cycles (Q1, Q2, Q3, and Q4). The instruction fetch and execute are pipelined such that fetch takes one instruction cycle while decode and execute takes another instruction cycle. However, due to the pipelining, each instruction effectively executes in one cycle. If an instruction causes the program counter to change (e.g.`GOTO`) then two cycles are required to complete the instruction (Example 3-2).

A fetch cycle begins with the program counter incrementing in Q1.

In the execution cycle, the fetched instruction is latched into the “Instruction Register (IR)” in cycle Q1. This instruction is then decoded and executed during the Q2, Q3, and Q4 cycles. Data memory is read during Q2 (operand read) and written during Q4 (destination write).

FIGURE 3-3: CLOCK/INSTRUCTION CYCLE



EXAMPLE 3-2: INSTRUCTION PIPELINE FLOW

	Tcy0	Tcy1	Tcy2	Tcy3	Tcy4	Tcy5
`1. MOVLW 55h`	Fetch 1	Execute 1				
`2. MOVWF PORTB`		Fetch 2	Execute 2			
`3. CALL SUB_1`			Fetch 3	Execute 3		
`4. BSF   PORTA, BIT3 (Forced NOP)`				Fetch 4	Flush	
`5. Instruction @ address SUB_1`					Fetch SUB_1	Execute SUB_1

All instructions are single cycle, except for any program branches. These take two cycles since the fetch instruction is “flushed” from the pipeline while the new instruction is being fetched and then executed.

7.0 TABLE READS AND TABLE WRITES

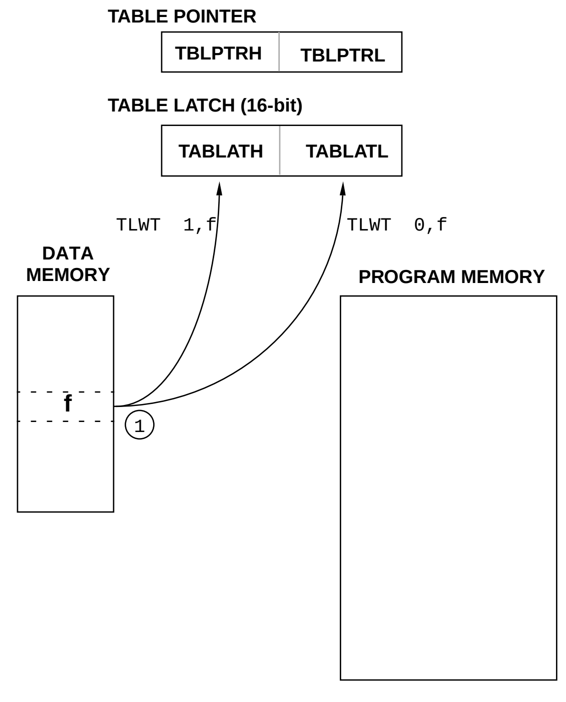
The PIC17C4X has four instructions that allow the processor to move data from the data memory space to the program memory space, and vice versa. Since the program memory space is 16-bits wide and the data memory space is 8-bits wide, two operations are required to move 16-bit values to/from the data memory.

The `TLWT t,f` and `TABLWT t,i,f` instructions are used to write data from the data memory space to the program memory space. The `TLRD t,f` and `TABLRD t,i,f` instructions are used to write data from the program memory space to the data memory space.

The program memory can be internal or external. For the program memory access to be external, the device needs to be operating in extended microcontroller or microprocessor mode.

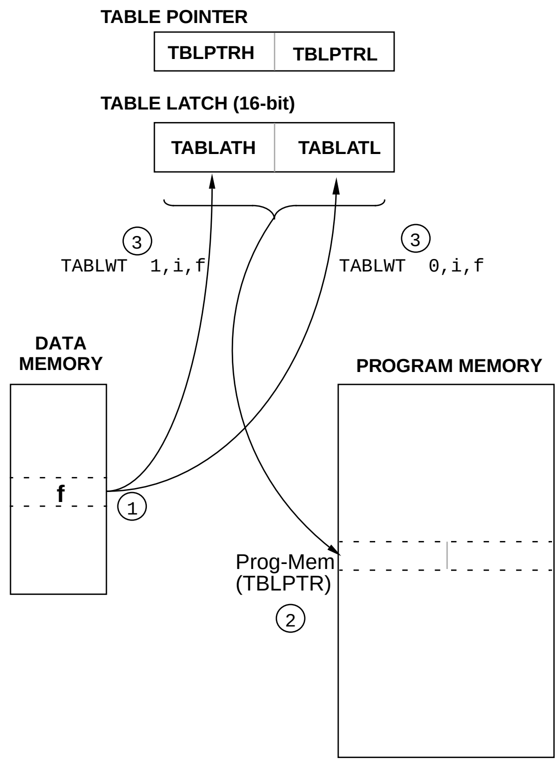
Figure 7-1 through Figure 7-4 show the operation of these four instructions.

FIGURE 7-1: TLWT INSTRUCTION OPERATION



Note 1: 8-bit value, from register 'f', loaded into the high or low byte in TABLAT (16-bit).

FIGURE 7-2: TABLWT INSTRUCTION OPERATION



Note 1: 8-bit value, from register 'f', loaded into the high or low byte in TABLAT (16-bit).
2: 16-bit TABLAT value written to address Program Memory (TBLPTR).
3: If “i” = 1, then TBLPTR = TBLPTR + 1,
If “i” = 0, then TBLPTR is unchanged.

NOTES:

9.4.1 PORTE AND DDRE REGISTER

PORTE is a 3-bit bi-directional port. The corresponding data direction register is DDRE. A '1' in DDRE configures the corresponding port pin as an input. A '0' in the DDRE register configures the corresponding port pin as an output. Reading PORTE reads the status of the pins, whereas writing to it will write to the port latch. PORTE is multiplexed with the system bus. When operating as the system bus, PORTE contains the control signals for the address/data bus (AD15:AD0). These control signals are Address Latch Enable (ALE), Output Enable ($\overline{OE}$), and Write ($\overline{WR}$). The control signals $\overline{OE}$ and $\overline{WR}$ are active low signals. The timing for the system bus is shown in the Electrical Characteristics section.

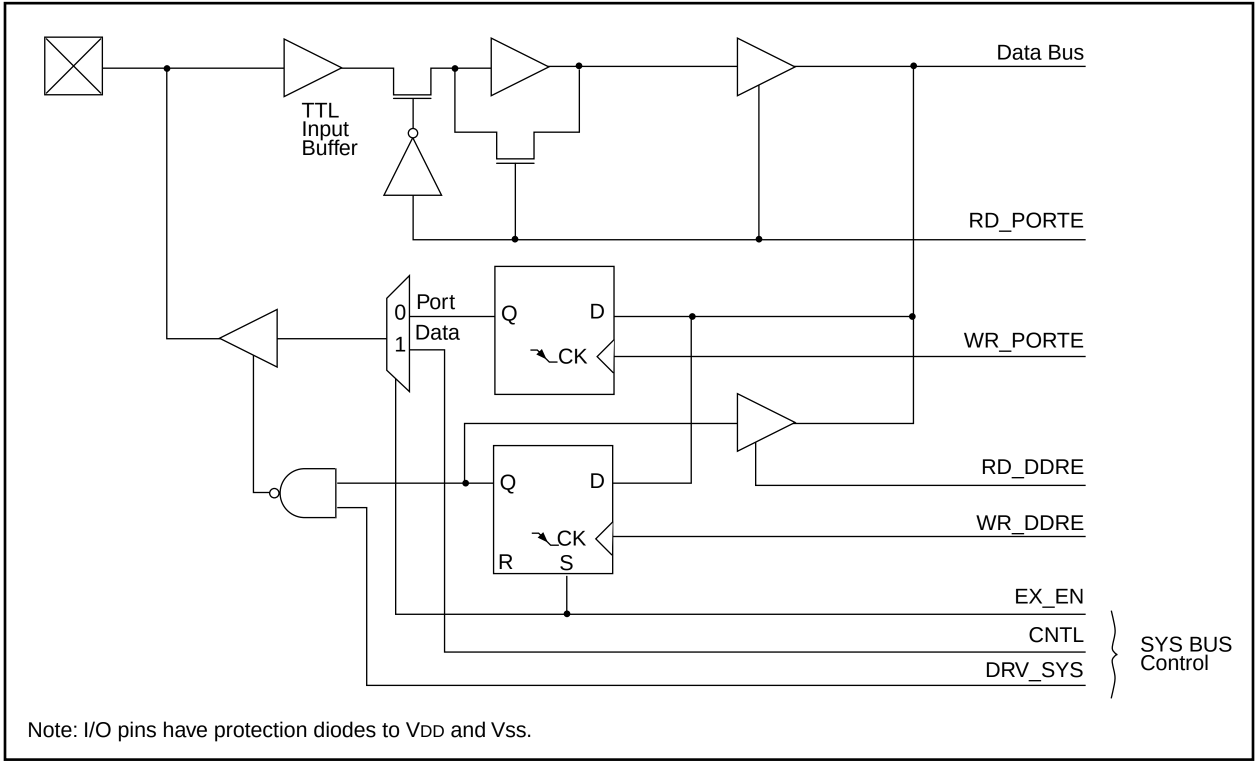
Note:	This port is configured as the system bus when the device's configuration bits are selected to Microprocessor or Extended Microcontroller modes. In the two other microcontroller modes, this port is a general purpose I/O.

Example 9-4 shows the instruction sequence to initialize PORTE. The Bank Select Register (BSR) must be selected to Bank 1 for the port to be initialized.

EXAMPLE 9-4: INITIALIZING PORTE

```
MOVLB  1           ;  Select Bank 1
CLRF   PORTE       ;  Initialize PORTE data
                   ;    latches before setting
                   ;    the data direction
                   ;    register
MOVLW  0x03        ;  Value used to initialize
                   ;   data direction
MOVWF  DDRE        ;  Set RE<1:0> as inputs
                   ;    RE<2> as outputs
                   ;    RE<7:3> are always
                   ;    read as '0'
```

FIGURE 9-8: PORTE BLOCK DIAGRAM (IN I/O PORT MODE)



Note: I/O pins have protection diodes to VDD and Vss.

TABLE 9-9: PORTE FUNCTIONS

Name	Bit	Buffer Type	Function
RE0/ALE	bit0	TTL	Input/Output or system bus Address Latch Enable (ALE) control pin.
RE1/$\overline{\text{OE}}$	bit1	TTL	Input/Output or system bus Output Enable ($\overline{\text{OE}}$) control pin.
RE2/$\overline{\text{WR}}$	bit2	TTL	Input/Output or system bus Write ($\overline{\text{WR}}$) control pin.

Legend: TTL = TTL input.

TABLE 9-10: REGISTERS/BITS ASSOCIATED WITH PORTE

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on Power-on Reset	Value on all other resets (Note1)
15h, Bank 1	PORTE	—	—	—	—	—	RE2/$\overline{\text{WR}}$	RE1/$\overline{\text{OE}}$	RE0/ALE	`---- -xxx`	`---- -uuu`
14h, Bank 1	DDRE	Data direction register for PORTE								`---- -111`	`---- -111`

Legend: x = unknown, u = unchanged, - = unimplemented read as '0'. Shaded cells are not used by PORTE.

Note 1: Other (non power-up) resets include: external reset through $\overline{\text{MCLR}}$ and the Watchdog Timer Reset.

INCF Increment f

Syntax: [*label*] INCF f,d

Operands: 0 ≤ f ≤ 255
d ∈ [0,1]

Operation: (f) + 1 → (dest)

Status Affected: OV, C, DC, Z

Encoding:

`0001`	`010d`	`ffff`	`ffff`

Description: The contents of register 'f' are incremented. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is placed back in register 'f'.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

Example:

```
INCF     CNT, 1
```

Before Instruction
CNT = 0xFF
Z = 0
C = ?

After Instruction
CNT = 0x00
Z = 1
C = 1

INCFSZ Increment f, skip if 0

Syntax: [*label*] INCFSZ f,d

Operands: 0 ≤ f ≤ 255
d ∈ [0,1]

Operation: (f) + 1 → (dest)
skip if result = 0

Status Affected: None

Encoding:

`0001`	`111d`	`ffff`	`ffff`

Description: The contents of register 'f' are incremented. If 'd' is 0 the result is placed in WREG. If 'd' is 1 the result is placed back in register 'f'.

If the result is 0, the next instruction, which is already fetched, is discarded, and an NOP is executed instead making it a two-cycle instruction.

Words: 1

Cycles: 1(2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write to destination

If skip:

Q1	Q2	Q3	Q4
Forced NOP	NOP	Execute	NOP

Example:

```
HERE    INCFSZ   CNT, 1
NZERO   :
ZERO    :
```

Before Instruction
PC = Address `(HERE)`

After Instruction
CNT = CNT + 1
If CNT = 0;
PC = Address`(ZERO)`
If CNT ≠ 0;
PC = Address`(NZERO)`

TLWT — Table Latch Write

Syntax: [*label*] TLWT t,f

Operands: 0 ≤ f ≤ 255
t ∈ [0,1]

Operation: If t = 0,
f → TBLATL;
If t = 1,
f → TBLATH

Status Affected: None

Encoding:

`1010`	`01tx`	`ffff`	`ffff`

Description: Data from file register 'f' is written into the 16-bit table latch (TBLAT).

If t = 1; high byte is written

If t = 0; low byte is written

This instruction is used in conjunction with `TABLWT` to transfer data from data memory to program memory.

Words: 1

Cycles: 1

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	Write register TBLATH or TBLATL

Example: `TLWT t, RAM`

Before Instruction
t = 0
RAM = 0xB7
TBLAT = 0x0000 (TBLATH = 0x00)
(TBLATL = 0x00)

After Instruction
RAM = 0xB7
TBLAT = 0x00B7 (TBLATH = 0x00)
(TBLATL = 0xB7)

Before Instruction
t = 1
RAM = 0xB7
TBLAT = 0x0000 (TBLATH = 0x00)
(TBLATL = 0x00)

After Instruction
RAM = 0xB7
TBLAT = 0xB700 (TBLATH = 0xB7)
(TBLATL = 0x00)

TSTFSZ — Test f, skip if 0

Syntax: [*label*] TSTFSZ f

Operands: 0 ≤ f ≤ 255

Operation: skip if f = 0

Status Affected: None

Encoding:

`0011`	`0011`	`ffff`	`ffff`

Description: If 'f' = 0, the next instruction, fetched during the current instruction execution, is discarded and an NOP is executed making this a two-cycle instruction.

Words: 1

Cycles: 1 (2)

Q Cycle Activity:

Q1	Q2	Q3	Q4
Decode	Read register 'f'	Execute	NOP

If skip:

Q1	Q2	Q3	Q4
Forced NOP	NOP	Execute	NOP

Example:

```
HERE    TSTFSZ  CNT
NZERO     :
ZERO    :
```

Before Instruction
PC = Address(`HERE`)

After Instruction
If CNT = 0x00,
PC = Address (`ZERO`)
If CNT ≠ 0x00,
PC = Address (`NZERO`)

TABLE 16-1: DEVELOPMENT TOOLS FROM MICROCHIP

Product	** MPLAB™ Integrated Development Environment	MPLAB™ C Compiler	MP-DriveWay Applications Code Generator	fuzzyTECH®-MP Explorer/Edition Fuzzy Logic Dev. Tool	*** PICMASTER®/ PICMASTER-CE In-Circuit Emulator	ICEPIC Low-Cost In-Circuit Emulator	****PRO MATE™ II Universal Microchip Programmer	PICSTART® Lite Ultra Low-Cost Dev. Kit	PICSTART® Plus Low-Cost Universal Dev. Kit
PIC12C508, 509	SW007002	SW006005	—	—	EM167015/ EM167101	—	DV007003	—	DV003001
PIC14000	SW007002	SW006005	—	—	EM147001/ EM147101	—	DV007003	—	DV003001
PIC16C52, 54, 54A, 55, 56, 57, 58A	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167015/ EM167101	EM167201	DV007003	DV162003	DV003001
PIC16C554, 556, 558	SW007002	SW006005	—	DV005001/ DV005002	EM167033/ EM167113	—-	DV007003	—	DV003001
PIC16C61	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167021/ N/A	EM167205	DV007003	DV162003	DV003001
PIC16C62, 62A, 64, 64A	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167025/ EM167103	EM167203	DV007003	DV162002	DV003001
PIC16C620, 621, 622	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167023/ EM167109	EM167202	DV007003	DV162003	DV003001
PIC16C63, 65, 65A, 73, 73A, 74, 74A	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167025/ EM167103	EM167204	DV007003	DV162002	DV003001
PIC16C642, 662*	SW007002	SW006005	—	—	EM167035/ EM167105	—-	DV007003	DV162002	DV003001
PIC16C71	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167027/ EM167105	EM167205	DV007003	DV162003	DV003001
PIC16C710, 711	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167027/ EM167105	—	DV007003	DV162003	DV003001
PIC16C72	SW007002	SW006005	SW006006	—	EM167025/ EM167103	—	DV007003	DV162002	DV003001
PIC16F83	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167029/ EM167107	—	DV007003	DV162003	DV003001
PIC16C84	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167029/ EM167107	EM167206	DV007003	DV162003	DV003001
PIC16F84	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167029/ EM167107	—	DV007003	DV162003	DV003001
PIC16C923, 924*	SW007002	SW006005	SW006006	DV005001/ DV005002	EM167031/ EM167111	—	DV007003	—	DV003001
PIC17C42, 42A, 43, 44	SW007002	SW006005	SW006006	DV005001/ DV005002	EM177007/ EM177107	—	DV007003	—	DV003001

*Contact Microchip Technology for availability date

**MPLAB Integrated Development Environment includes MPLAB-SIM Simulator and MPASM Assembler

***All PICMASTER and PICMASTER-CE ordering part numbers above include PRO MATE II programmer

****PRO MATE socket modules are ordered separately. See development systems ordering guide for specific ordering part numbers

Product	TRUEGAUGE® Development Kit	SEEVAL® Designers Kit	Hopping Code Security Programmer Kit	Hopping Code Security Eval/Demo Kit
All 2 wire and 3 wire Serial EEPROM's	N/A	DV243001	N/A	N/A
MTA11200B	DV114001	N/A	N/A	N/A
HCS200, 300, 301 *	N/A	N/A	PG306001	DM303001

Applicable Devices	42	R42	42A	43	R43	44

TABLE 17-1: CROSS REFERENCE OF DEVICE SPECS FOR OSCILLATOR CONFIGURATIONS AND FREQUENCIES OF OPERATION (COMMERCIAL DEVICES)

OSC	PIC17C42-16	PIC17C42-25
RC	VDD: 4.5V to 5.5V IDD: 6 mA max. IPD: 5 µA max. at 5.5V (WDT disabled) Freq: 4 MHz max.	VDD: 4.5V to 5.5V IDD: 6 mA max. IPD: 5 µA max. at 5.5V (WDT disabled) Freq: 4 MHz max.
XT	VDD: 4.5V to 5.5V IDD: 24 mA max. IPD: 5 µA max. at 5.5V (WDT disabled) Freq: 16 MHz max.	VDD: 4.5V to 5.5V IDD: 38 mA max. IPD: 5 µA max. at 5.5V (WDT disabled) Freq: 25 MHz max.
EC	VDD: 4.5V to 5.5V IDD: 24 mA max. IPD: 5 µA max. at 5.5V (WDT disabled) Freq: 16 MHz max.	VDD: 4.5V to 5.5V IDD: 38 mA max. IPD: 5 µA max. at 5.5V (WDT disabled) Freq: 25 MHz max.
LF	VDD: 4.5V to 5.5V IDD: 150 µA max. at 32 kHz (WDT enabled) IPD: 5 µA max. at 5.5V (WDT disabled) Freq: 2 MHz max.	VDD: 4.5V to 5.5V IDD: 150 µA max. at 32 kHz (WDT enabled) IPD: 5 µA max. at 5.5V (WDT disabled) Freq: 2 MHz max.

Applicable Devices	42	R42	42A	43	R43	44

17.2 DC CHARACTERISTICS: PIC17C42-16 (Commercial, Industrial)
PIC17C42-25 (Commercial, Industrial)

DC CHARACTERISTICS

Standard Operating Conditions (unless otherwise stated)
Operating temperature
-40˚C ≤ TA ≤ +85˚C for industrial and
0˚C ≤ TA ≤ +70˚C for commercial
Operating voltage VDD range as described in Section 17.1

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
		Input Low Voltage					
	VIL	I/O ports					
D030		with TTL buffer	VSS	–	0.8	V	
D031		with Schmitt Trigger buffer	VSS	–	0.2VDD	V	
D032		$\overline{\text{MCLR}}$, OSC1 (in EC and RC mode)	Vss	–	0.2VDD	V	Note1
D033		OSC1 (in XT, and LF mode)	–	0.5VDD	–	V	
		Input High Voltage					
	VIH	I/O ports		–			
D040		with TTL buffer	2.0	–	VDD	V	
D041		with Schmitt Trigger buffer	0.8VDD	–	VDD	V	
D042		$\overline{\text{MCLR}}$	0.8VDD	–	VDD	V	Note1
D043		OSC1 (XT, and LF mode)	–	0.5VDD	–	V	
D050	VHYS	Hysteresis of Schmitt Trigger inputs	0.15VDD*	–	–	V	
		Input Leakage Current (Notes 2, 3)					
D060	IIL	I/O ports (except RA2, RA3)	–	–	±1	µA	Vss ≤ VPIN ≤ VDD, I/O Pin at hi-impedance PORTB weak pull-ups disabled
D061		$\overline{\text{MCLR}}$	–	–	±2	µA	VPIN = Vss or VPIN = VDD
D062		RA2, RA3			±2	µA	Vss ≤ VRA2, VRA3 ≤ 12V
D063		OSC1, TEST	–	–	±1	µA	Vss ≤ VPIN ≤ VDD
D064		$\overline{\text{MCLR}}$	–	–	10	µA	VMCLR = VPP = 12V (when not programming)
D070	IPURB	PORTB weak pull-up current	60	200	400	µA	VPIN = VSS, $\overline{\text{RBPU}}$ = 0

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

‡ These parameters are for design guidance only and are not tested, nor characterized.

†† Design guidance to attain the AC timing specifications. These loads are not tested.

Note 1: In RC oscillator configuration, the OSC1 pin is a Schmitt Trigger input. It is not recommended that the PIC17CXX devices be driven with external clock in RC mode.

2: The leakage current on the $\overline{\text{MCLR}}$ pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as coming out of the pin.

4: These specifications are for the programming of the on-chip program memory EPROM through the use of the table write instructions. The complete programming specifications can be found in: PIC17CXX Programming Specifications (Literature number DS30139).

5: The $\overline{\text{MCLR}}$/Vpp pin may be kept in this range at times other than programming, but this is not recommended.

6: For TTL buffers, the better of the two specifications may be used.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 18-5: TRANSCONDUCTANCE (gm) OF LF OSCILLATOR vs. VDD

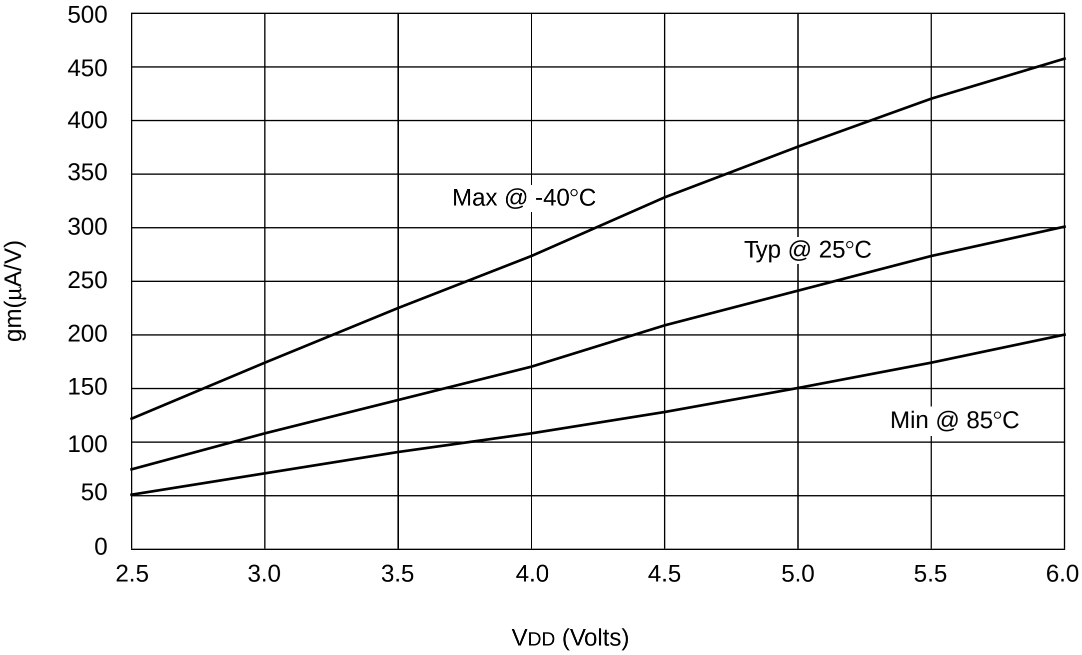
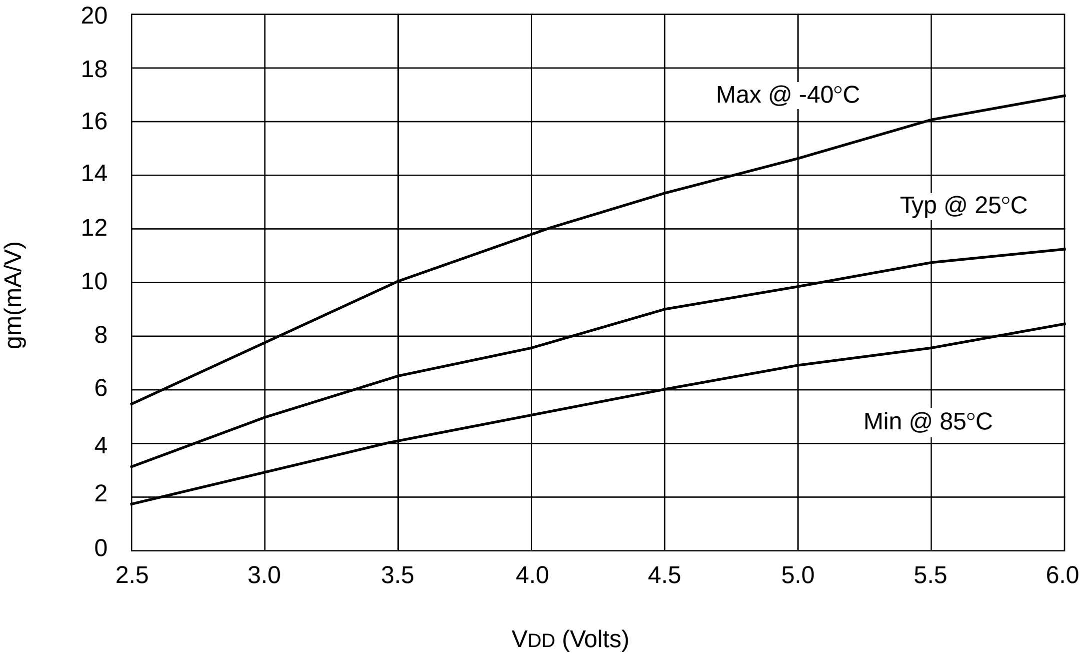


FIGURE 18-6: TRANSCONDUCTANCE (gm) OF XT OSCILLATOR vs. VDD



Applicable Devices	42	R42	42A	43	R43	44

FIGURE 18-7: TYPICAL IDD vs. FREQUENCY (EXTERNAL CLOCK 25°C)

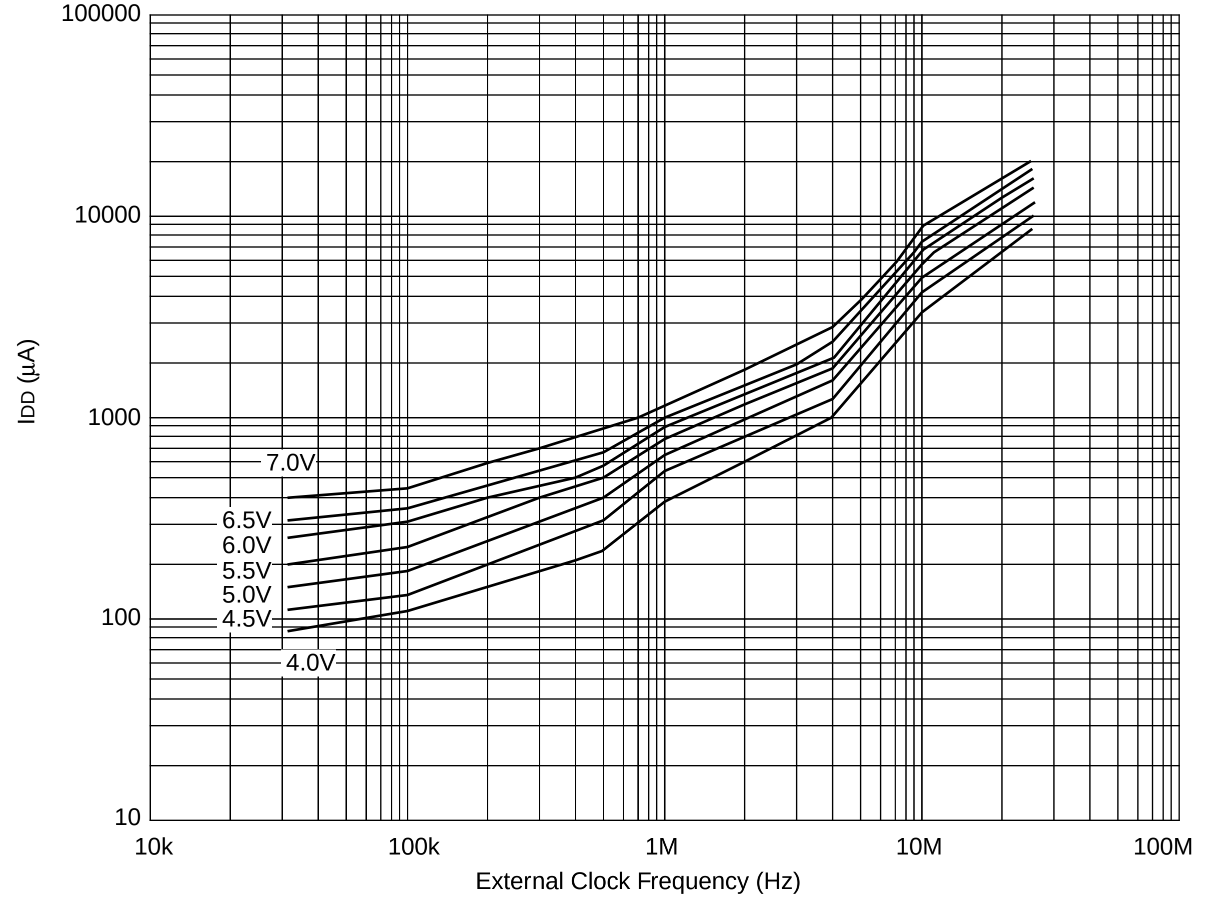
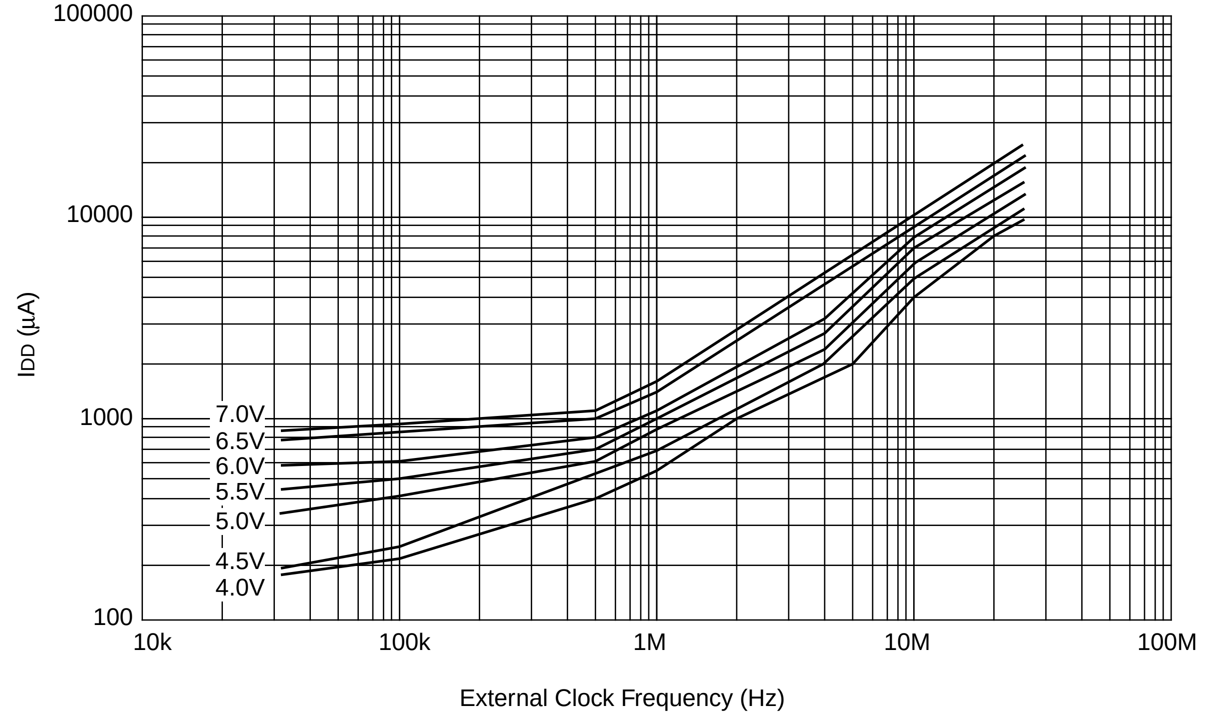


FIGURE 18-8: MAXIMUM IDD vs. FREQUENCY (EXTERNAL CLOCK 125°C TO -40°C)



Applicable Devices	42	R42	42A	43	R43	44

19.0 PIC17CR42/42A/43/R43/44 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Ambient temperature under bias	-55 to +125°C
Storage temperature	-65°C to +150°C
Voltage on V_{DD} with respect to V_{SS}	0 to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} (Note 2)	-0.6V to +14V
Voltage on RA2 and RA3 with respect to V_{SS}	-0.6V to +14V
Voltage on all other pins with respect to V_{SS}	-0.6V to V_{DD} + 0.6V
Total power dissipation (Note 1)	1.0W
Maximum current out of V_{SS} pin(s) - total	250 mA
Maximum current into V_{DD} pin(s) - total	200 mA
Input clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	±20 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$)	±20 mA
Maximum output current sunk by any I/O pin (except RA2 and RA3)	35 mA
Maximum output current sunk by RA2 or RA3 pins	60 mA
Maximum output current sourced by any I/O pin	20 mA
Maximum current sunk by PORTA and PORTB (combined)	150 mA
Maximum current sourced by PORTA and PORTB (combined)	100 mA
Maximum current sunk by PORTC, PORTD and PORTE (combined)	150 mA
Maximum current sourced by PORTC, PORTD and PORTE (combined)	100 mA

Note 1: Power dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

Note 2: Voltage spikes below V_{SS} at the $\overline{MCLR}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}$ pin rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

19.1 DC CHARACTERISTICS: PIC17CR42/42A/43/R43/44-16 (Commercial, Industrial)
PIC17CR42/42A/43/R43/44-25 (Commercial, Industrial)
PIC17CR42/42A/43/R43/44-33 (Commercial, Industrial)

DC CHARACTERISTICS			**Standard Operating Conditions (unless otherwise stated)** Operating temperature -40˚C ≤ TA ≤ +85˚C for industrial and 0˚C ≤ TA ≤ +70˚C for commercial				
Parameter No.	**Sym**	**Characteristic**	**Min**	**Typ†**	**Max**	**Units**	**Conditions**
D001	VDD	Supply Voltage	4.5	–	6.0	V	
D002	VDR	RAM Data Retention Voltage (Note 1)	1.5 *	–	–	V	Device in SLEEP mode
D003	VPOR	VDD start voltage to ensure internal Power-on Reset signal	–	VSS	–	V	See section on Power-on Reset for details
D004	SVDD	VDD rise rate to ensure internal Power-on Reset signal	0.060 *	–	–	mV/ms	See section on Power-on Reset for details
D010	IDD	Supply Current (Note 2)	–	3	6	mA	FOSC = 4 MHz (Note 4)
D011			–	6	12 *	mA	FOSC = 8 MHz
D012			–	11	24 *	mA	FOSC = 16 MHz
D013			–	19	38	mA	FOSC = 25 MHz
D015			–	25	50	mA	FOSC = 33 MHz
D014			–	95	150	µA	FOSC = 32 kHz, WDT enabled (EC osc configuration)
D020	IPD	Power-down Current (Note 3)	–	10	40	µA	VDD = 5.5V, WDT enabled
D021			–	< 1	5	µA	VDD = 5.5V, WDT disabled

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25˚C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail to rail; all I/O pins tristated, pulled to VDD or VSS, T0CKI = VDD,
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.
Current consumed from the oscillator and I/O's driving external capacitive or resistive loads needs to be considered.
For the RC oscillator, the current through the external pull-up resistor (R) can be estimated as: VDD / (2 • R).
For capacitive loads, the current can be estimated (for an individual I/O pin) as (CL • VDD) • f
CL = Total capacitive load on the I/O pin; f = average frequency the I/O pin switches.
The capacitive currents are most significant when the device is configured for external execution (includes extended microcontroller mode).

3: The power down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD and VSS.

4: For RC osc configuration, current through Rext is not included. The current through the resistor can be estimated by the formula IR = VDD/2Rext (mA) with Rext in kOhm.

Applicable Devices	42	R42	42A	43	R43	44

FIGURE 19-12: MEMORY INTERFACE READ TIMING (NOT SUPPORTED IN PIC17LC4X DEVICES)

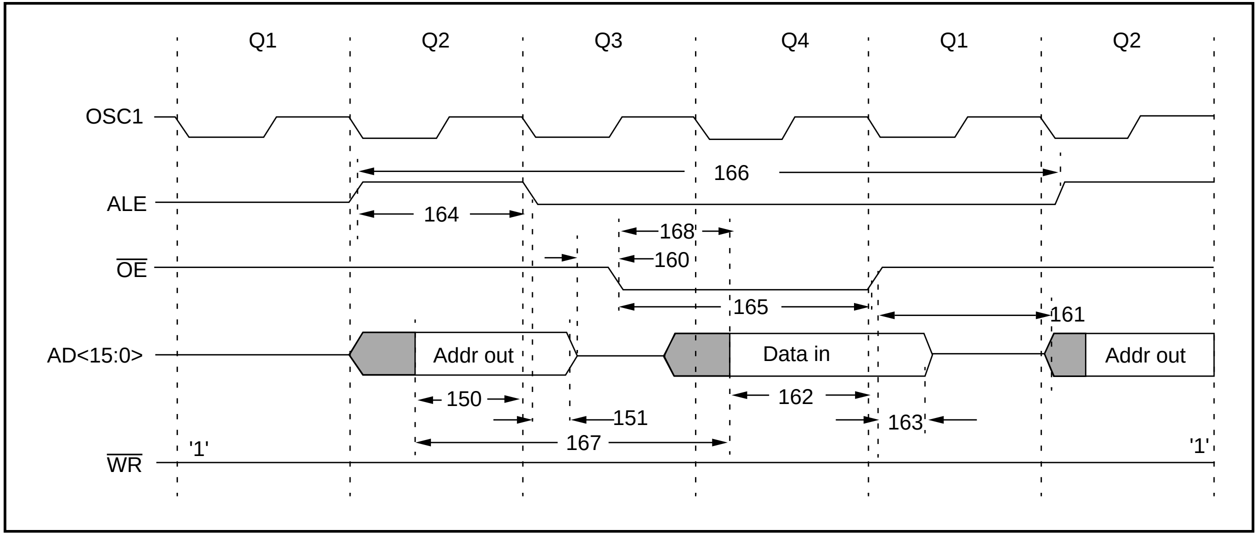


TABLE 19-12: MEMORY INTERFACE READ REQUIREMENTS (NOT SUPPORTED IN PIC17LC4X DEVICES)

Parameter No.	Sym	Characteristic	Min	Typ†	Max	Units	Conditions
150	TadV2alL	AD15:AD0 (address) valid to ALE↓ (address setup time)	0.25Tcy - 10	—	—	ns	
151	TalL2adI	ALE↓ to address out invalid (address hold time)	5*	—	—	ns	
160	TadZ2oeL	AD15:AD0 hi-impedance to $\overline{OE}$↓	0*	—	—	ns	
161	ToeH2adD	$\overline{OE}$↑ to AD15:AD0 driven	0.25Tcy - 15	—	—	ns	
162	TadV2oeH	Data in valid before $\overline{OE}$↑ (data setup time)	35	—	—	ns	
163	ToeH2adI	$\overline{OE}$↑to data in invalid (data hold time)	0	—	—	ns	
164	TalH	ALE pulse width	—	0.25TCY §	—	ns	
165	ToeL	$\overline{OE}$ pulse width	0.5Tcy - 35 §	—	—	ns	
166	TalH2alH	ALE↑ to ALE↑(cycle time)	—	TCY §	—	ns	
167	Tacc	Address access time	—	—	0.75TCY - 30	ns	
168	Toe	Output enable access time ($\overline{OE}$ low to Data Valid)	—	—	0.5TCY - 45	ns	

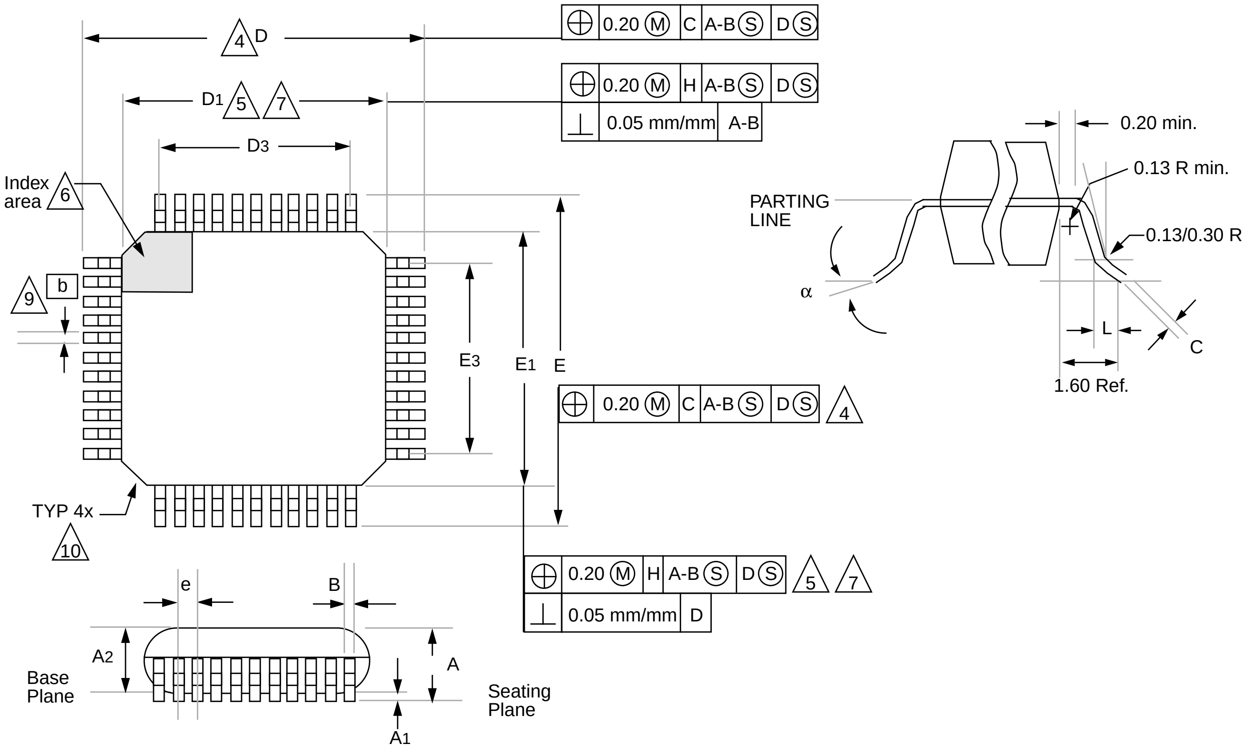
* These parameters are characterized but not tested.

† Data in “Typ” column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

§ This specification ensured by design.

NOTES:

21.4 44-Lead Plastic Surface Mount (MQFP 10x10 mm Body 1.6/0.15 mm Lead Form)



Package Group: Plastic MQFP						
	Millimeters			Inches		
Symbol	Min	Max	Notes	Min	Max	Notes
α	0°	7°		0°	7°	
A	2.000	2.350		0.078	0.093	
A1	0.050	0.250		0.002	0.010	
A2	1.950	2.100		0.768	0.083	
b	0.300	0.450	**Typical**	0.011	0.018	**Typical**
C	0.150	0.180		0.006	0.007	
D	12.950	13.450		0.510	0.530	
D1	9.900	10.100		0.390	0.398	
D3	8.000	8.000	**Reference**	0.315	0.315	**Reference**
E	12.950	13.450		0.510	0.530	
E1	9.900	10.100		0.390	0.398	
E3	8.000	8.000	**Reference**	0.315	0.315	**Reference**
e	0.800	0.800		0.031	0.032	
L	0.730	1.030		0.028	0.041	
N	44	44		44	44	
CP	0.102	–		0.004	–	

E.3 PIC16CXXX Family of Devices

	Clock	Memory		Peripherals			Features				
	Maximum Frequency of Operation (MHz)	Program Memory (x14 words) EPROM	Data Memory (bytes)	Timer Module(s)	Comparator(s)	Internal Reference Voltage	Interrupt Sources	I/O Pins	Voltage Range (Volts)	Brown-out Reset	Packages
PIC16C554	20	512	80	TMR0	—	—	3	13	2.5-6.0	—	18-pin DIP, SOIC; 20-pin SSOP
PIC16C556	20	1K	80	TMR0	—	—	3	13	2.5-6.0	—	18-pin DIP, SOIC; 20-pin SSOP
PIC16C558	20	2K	128	TMR0	—	—	3	13	2.5-6.0	—	18-pin DIP, SOIC; 20-pin SSOP
PIC16C620	20	512	80	TMR0	2	Yes	4	13	2.5-6.0	Yes	18-pin DIP, SOIC; 20-pin SSOP
PIC16C621	20	1K	80	TMR0	2	Yes	4	13	2.5-6.0	Yes	18-pin DIP, SOIC; 20-pin SSOP
PIC16C622	20	2K	128	TMR0	2	Yes	4	13	2.5-6.0	Yes	18-pin DIP, SOIC; 20-pin SSOP

All PIC16/17 Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability.

All PIC16C6XXX Family devices use serial programming with clock pin RB6 and data pin RB7.

NOTES: